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ABSTRACT OF THE DISCLOSURE[1]:

METHOD FOR THE PATTERN-PROCESSING OF PHOTOSENSITIVE RESIN COMPOSITION

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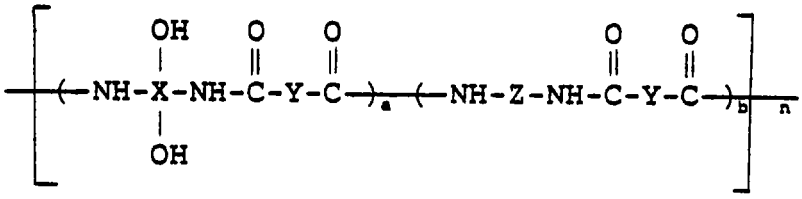
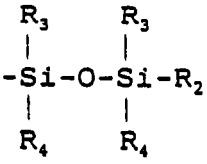
A method of the pattern-processing of a photosensitive resin composition which comprises coating on a substrate a positive photosensitive resin composition comprising a polyamide represented by the following formula (1) and a diazoquinone compound, subjecting the same to prebaking and then to irradiation with a light, thereafter dissolving the exposed portion in an alkaline aqueous solution containing an anionic surfactant to remove the same, thereby obtaining a pattern. When the development is effected with the alkaline aqueous solution containing an anionic surfactant of this invention, a scum-free, very high resolution pattern can be obtained:



(1)

wherein X is a tetravalent aromatic group; Y is a



divalent group; Z is

in which R_1 and R_2 are divalent organic groups and R_3 and R_4 are monovalent organic groups; a and b are mole fractions; a + b = 100 mole %; a = 60.0 - 100 mole %; b = 0 -

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21 DEC 1996

40.0 mole % and n = 2 - 500.